

### **Amendments to the Specification**

Please amend a paragraph [0018] as follows:

The first surface 37 and a plurality of lateral sides 47 of the die 36 are encapsulated by the mold compound 46. The lateral sides 47 extend between the opposed first and second surfaces 37 and 43 of the die 36. Additionally, the mold compound 46 is fused with the heat spreader lid 34 and the die carrier 32, the mold compound 46 being in contact with a surface of the die carrier 32 and a surface of the heat spreader lid 34 that is parallel to the surface to the die carrier 32. The mold compound 46, heat spreader lid 34, die carrier 32, and die 36 are fused into a one piece, solid structure by a one-time curing process to be described hereinafter. This fusion into a solid structure may cause stress to be distributed evenly throughout the die 36, mold compound 46, die carrier 32 and heat spreader lid 34. The polymeric property of the mold compound 46 may provide a cushioning effect for the die 36.